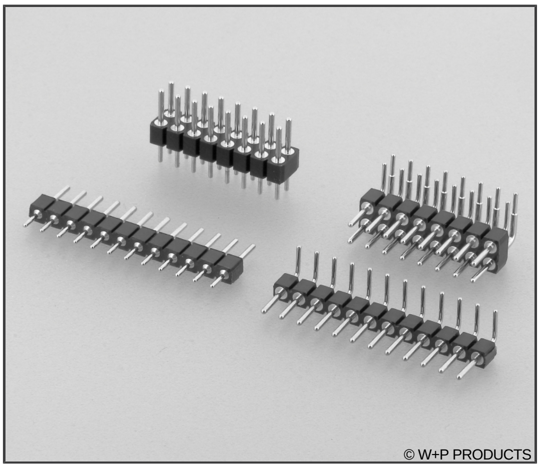
330

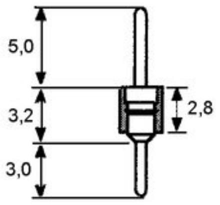
Adapter-Leisten RM 2,54mm, gerade/gewinkelt - Spezialkontakte 0,76/0,60mm

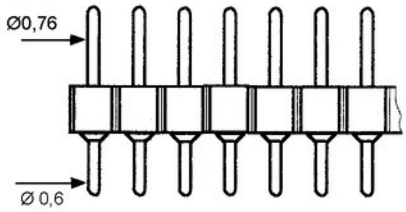
Adapter Headers, 2.54mm Pitch, Straight/Right-Angled – 0.76/0.60mm Contacts

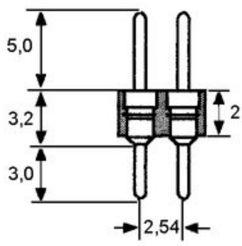
Technische Daten / *Technical Data*

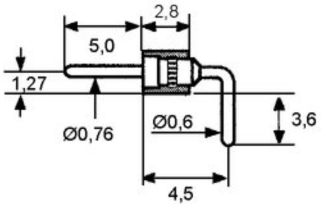
Isolierkörper	Thermoplastischer Kunststoff, nach UL94 V-0
Insulator	*Thermoplastic, rated UL94 V-0*
Kontaktmaterial	Messing gedreht
Contact Material	*Screw machined brass*
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni (2 ... 3µm)
Contact Surface	*Acc. to options (see below), over Ni (2 ... 3µm)*
Durchgangswiderstand	< 10mΩ
Contact Resistance	*< 10mΩ*
Isolationswiderstand	> 1000MΩ
Insulation Resistance	*> 1000MΩ*
Spannungsfestigkeit	$1kV_{RMS}$
Test Voltage	$1kV_{RMS}$
Nennspannung	$100V_{RMS}$ / $150V_{DC}$
Voltage Rating	$100V_{RMS}$ / $150V_{DC}$
Nennstrom	3A
Current Rating	*3A*
Temperaturbereich	-55°C ... +125°C
Temperature Range	*-55°C ... +125°C*
Verarbeitung	Wellen- oder Reflow-Lötverfahren
Processing	*Wave or reflow soldering*

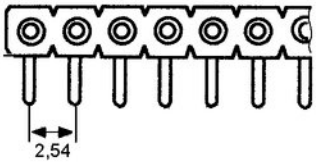


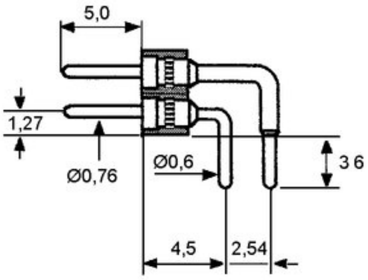












Series	***Contacts****	***Terminal****	***Plating****
330	01	11	00
	01-64 Einreihig *Single row* **02-64** Zweireihig *Double row*	**10** Einreihig, gerade *Single row, straight* **20** Zweireihig, gerade *Double row, straight* **11** Einreihig, gewinkelt *Single row, right angled* **21** Zweireihig, gewinkelt *Double row, right angled*	**00** Vergoldet *Gold plated* **10** Vergoldet 0,25µm (Option) *0.25µm gold plated (Option)* **50** Zinn 5,0µm *5.0µm tin plated*

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
** This is an **order example** -*
please replace by your specifications.

Informationen zum Reflow-Lötverfahren
Reflow Soldering Information

Reflow-Lötempfehlung
Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_S$min	150°C
Temperatur Maximum $T_S$max	200°C
Dauer $T_S$min - $T_S$max	60-180s
Temperatur Lötbereich T_L	217°C
Verweildauer oberhalb T_L	60-180s
Ramp-Up Rate $T_S$max - T_P	max. 3°C / s
Höchsttemperatur T_P	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_P$max - $T_S$min	6°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_S$min	*150°C*
Maximum Temperatur $T_S$max	*200°C*
Duration $T_S$min - $T_S$max	*60-180s*
Soldering Range Temperature T_L	*217°C*
Duration above T_L	*60-180s*
Ramp-Up Rate $T_S$max - T_P	*max. 3°C / s*
Peak Temperature T_P	*260°C ±5*
Duration Peak Temperature	*20-40s*
Ramp-Down Rate $T_P$max - $T_S$min	*6°C / s*
Duration 25°C - Peak Temp. T_P	*Max. 8min*